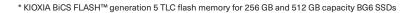


KIOXIA BG6 Series (M.2)

Client NVMe™ SSD

KIOXIA BG6 Series is a line-up of compact form factor NVMe™ SSDs with capacities up to 2,048 GB, and leverages a PCle[®] 4.0, NVMe[™] 1.4c specification compliant interface and KIOXIA BiCS FLASH™ generation 6 TLC flash memory*. With higher bandwidth, improved flash management and Host Memory Buffer (HMB) technology, the BG6 Series SSDs deliver very high read performance for compact form factor SSDs of up to 6,000 MB/s (sequential read) and up to 900K IOPS (random read).

KIOXIA BG6 Series SSDs are available in capacities of 256 GB, 512 GB, 1,024 GB and 2,048 GB in M.2 Type 2230 and Type 2280 module form factors, making them suitable for thin and light system designs, such as ultra-thin PCs. The BG6 Series offers a Self-Encrypting Drive (SED) model option, supporting TCG Opal Version 2.01.





M.2 2230



M 2 2280

Product image may represent a design model.

Key Features

- KIOXIA BiCS FLASH™ generation 6 TLC flash memory (KIOXIA BiCS FLASH™ generation 5 TLC flash memory for 256 GB and 512 GB)
- PCle[®] 4.0, NVMe[™] 1.4c specification compliant
- · Capacities up to 2,048 GB
- M.2 Type 2230 and Type 2280 single-sided form factors
- TCG Opal 2.01 SED option

Key Applications

- Ultra-mobile PCs
- · 2-in-1 notebook PCs

Specifications

| Base Model Number | KBG60ZNS 2T04 | KBG60ZNS 1T02 | KBG60ZNS 512G | KBG60ZNS 256G | KBG60ZNV 2T04 | KBG60ZNV 1T02 | KBG60ZNV 512G | KBG60ZNV 256G | |
|----------------------------|-----------------------------|--------------------------|------------------|------------------|-----------------------------|--------------------------|------------------|------------------|--|
| SED Model Number | KBG6AZNS 2T04 | KBG6AZNS 1T02 | KBG6AZNS 512G | KBG6AZNS 256G | KBG6AZNV 2T04 | KBG6AZNV 1T02 | KBG6AZNV 512G | KBG6AZNV 256G | |
| Capacity | 2,048 GB | 1,024 GB | 512 GB | 256 GB | 2,048 GB | 1,024 GB | 512 GB | 256 GB | |
| Basic Specifications | | | | | | | | | |
| Form Factor | M.2 2230-S3 Single-sided | M.2 2230-S2 Single-sided | | | M.2 2280-S3 Single-sided | M.2 2280-S2 Single-sided | | | |
| Interface | PCIe® 4.0, NVMe™ 1.4c | | | | | | | | |
| Maximum Interface Speed | 64 GT/s (PCIe® Gen4 x4) | | | | | | | | |
| Flash Memory Type | BiCS FLASH™ TLC | | | | | | | | |

Specifications (Continued)

| Capacity | 2,048 GB | 1,024 GB | 512 GB | 256 GB | 2,048 GB | 1,024 GB | 512 GB | 256 GB | | |
|--------------------------------|---|--------------------------|--------------------|-----------------|-----------------------------|--------------------------|------------|------------|--|--|
| Form Factor | M.2 2230-S3 Single-sided | M.2 2230-S2 Single-sided | | | M.2 2280-S3 Single-sided | M.2 2280-S2 Single-sided | | | | |
| Performance (Up to) | | | | | | | | | | |
| Sequential Read | 6,000 MB/s | | 4,800 MB/s | 4,400 MB/s 6,00 | | MB/s | 4,800 MB/s | 4,400 MB/s | | |
| Sequential Write | 5,300 MB/s | 5,000 MB/s | 4,000 MB/s | 3,000 MB/s | 5,300 MB/s | 5,000 MB/s | 4,000 MB/s | 3,000 MB/s | | |
| Random Read | 900K IOPS | 650K | 650K IOPS 350K IOF | | 900K IOPS | 650K IOPS | | 350K IOPS | | |
| Random Write | 900K | IOPS 850K IOPS 700K IOPS | | | 900K | CIOPS 850K IOPS | | 700K IOPS | | |
| Power Requirements | | | | | | | | | | |
| Supply Voltage | 3.3 V ± 5 % | | | | | | | | | |
| Power Consumption (Active) | 4.4 W typ. | 4.3 W typ. | 4.7 W typ. | 4.3 W typ. | 4.4 W typ. | 4.3 W typ. | 4.7 W typ. | 4.3 W typ. | | |
| Power Consumption (L1.2 mode) | 3.0 mW typ. | | | | | | | | | |
| Reliability | | | | | | | | | | |
| MTTF | 1,500,000 hours | | | | | | | | | |
| TBW | 1,200 | 600 | 300 | 150 | 1,200 | 600 | 300 | 150 | | |
| Dimensions | | | | | | | | | | |
| Thickness | 2.38 mm Max | 2.23 mm Max | | | 2.38 mm Max 2.23 mm Max | | | | | |
| Width | 22 mm ± 0.15 mm | | | | | | | | | |
| Length | | 30 mm ± 0.15 mm | | | 80 mm ± 0.15 mm | | | | | |
| Weight | 3.0 g Max | 2.9 g Max | 2.8 g Max | 2.7 g Max | 6.0 g Max | 5.9 g Max | 5.8 g Max | 5.7 g Max | | |
| Environmental | | | | | | | | | | |
| Temperature (Operating) | 0 °C to 95 °C (Controller Temperature) | | | | | | | | | |
| Temperature (Operating) | 0 °C to 85 °C (Other Components Temperature) | | | | | | | | | |
| Temperature (Non-operating) | -40 °C to 85 °C | | | | | | | | | |
| Humidity (Operating) | 0 % to 90 % R.H. | | | | | | | | | |
| Vibration (Operating) | 196 m/s² { 20 Grms } (20 to 2,000 Hz) | | | | | | | | | |
| Shock (Operating) | 14.7 km/s ² { 1,500 G } (0.5 ms) | | | | | | | | | |

Availability of the SED model line-up may vary by region.

Definition of capacity: KIOXIA Corporation defines a megabyte (MB) as 1,000,000 bytes, a gigabyte (GB) as 1,000,000,000 bytes and a terabyte (TB) as 1,000,000,000,000 bytes. A computer operating system, however, reports storage capacity using powers of 2 for the definition of 1 GB = 2^30 = 1,073,741,824 bytes and therefore shows less storage capacity. Available storage capacity (including examples of various media files) will vary based on file size, formatting, settings, software and operating system, such as Microsoft Operating System and/or pre-installed software applications, or media content. Actual formatted capacity may vary.

IOPS: Input Output Per Second (or the number of I/O operations per second).

 $TBW: Terabytes \ Written. \ The \ number \ of \ terabytes \ that \ may \ be \ written \ to \ the \ SSD \ for \ the \ specified \ lifetime.$

Read and write speed, tested on the state of "Host Memory Buffer (HMB) = On", may vary depending on the host device, read and write conditions, and file size.

Read and write speed may vary depending on various factors such as host devices, software (drivers, OS etc.), and read/write conditions.

MTTF (Mean Time to Failure) is not a guarantee or estimate of product life; it is a statistical value related to mean failure rates for a large number of products which may not accurately reflect actual operation. Actual operating life of the product may be different from the MTTF.

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